



P-22 I I-MIL POLYIMIDE FILM TAPE, AMBER

APPLICATION

The ultimate in circuit board protection! Thin and conformable, with outstanding puncture, tear and abrasion resistance at elevated temperatures.

Provides **optimal protection of gold fingers** during the wave soldering of printed wiring board. Also used to **mask circuit boards** during conformal coating, and for **reinforcing splices** on rolls of flexible circuits during "roll processing" as they go thru plating, etching and soldering stages.

FEATURES AND BENEFITS

- Perfect PCB protection tape thin, conformable, outstanding puncture and abrasion resistance, and withstands high temperature operating conditions.
- Aggressive, solvent resistant and high temperature silicone adhesive compliments the polyimide backing leaves no adhesive residue upon removal.
- Can be applied prior to component insertion and moisture-removing bake cycles with no change in performance level.
- Offers uniform unwind in long-length rolls, promoting automated applications.
- UL component recognized under File E20392.

TECHNICAL DATA

Insulation class Backing material Adhesive Total tape thickness Color Adhesion to steel Tensile strength Dielectric strength Elongation Unwind @ 150 FPM Insulation resistance Flammability rating UL component recog. 180° C
I-mil polyimide film
Silicone, cured
2.75 mils/0.069 mm
Amber
25 oz. per in./278 gm per cm
30 lbs. per in./5.3 kg per cm
7,500 volts
60%
45 oz. per in./501 gm per cm
I x 10⁶ megohms
Complies w/UL-510 Standard
Guide OANZ2,File E20392

Note: The above are typical values and should not be used in writing specifications.

STOCK SIZES

Refer to current Electronic Division Price List.

For Additional Information on this Product, Call Toll-Free 1-800-755-TAPE.